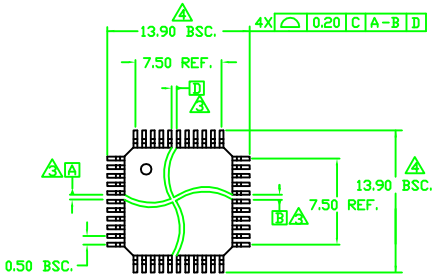
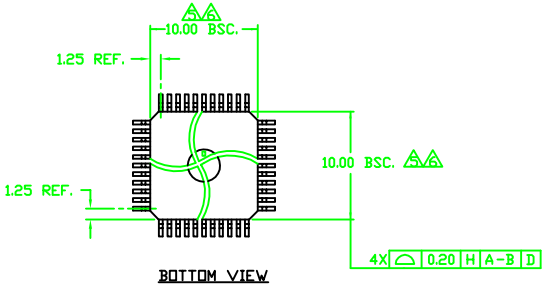
REV.	DESCRIPTION	DATE	ORIGINATOR
00	INITIAL RELEASE PER DCN #P70805.	11/19 1997	L.S.E.

NOTES:

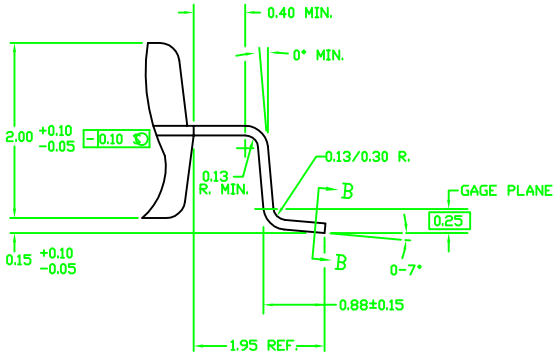
1. ALL DIMENSIONS AND TOLERANCES CONFORM TO ASME Y14.5M-1994.
2. DATUM PLANE H LOCATED AT MOLD PARTING LINE AND COINCIDENT WITH LEAD, WHERE LEAD EXITS PLASTIC BODY AT BOTTOM OF PARTING LINE.
3. DATUMS A-B AND D TO BE DETERMINED WHERE CENTERLINE BETWEEN LEADS EXITS PLASTIC BODY AT DATUM PLANE H.
4. TO BE DETERMINED AT SEATING PLANE C.
5. DIMENSIONS 10.00 OF BOTTOM VIEW DO NOT INCLUDE MOLD PROTRUSION. ALLOWABLE MOLD PROTRUSION IS 0.254MM PER SIDE. THESE DIMENSIONS DO INCLUDE MOLD MISMATCH AND ARE DETERMINED AT DATUM PLANE H.
6. PACKAGE TOP DIMENSIONS ARE SMALLER THAN BOTTOM DIMENSIONS BY 0.20 MM, AND TOP OF PACKAGE WILL NOT OVERHANG BOTTOM OF PACKAGE.
7. DIMENSION 0.15/0.30 OF SECTION 'B-B' DOES NOT INCLUDE DAMBAR PROTRUSION. ALLOWABLE DAMBAR PROTRUSION SHALL BE 0.08MM TOTAL IN EXCESS OF THE THIS DIMENSION AT MAXIMUM MATERIAL CONDITION. DAMBAR CANNOT BE LOCATED ON THE LOWER RADIUS OR THE FOOT.
8. ALL DIMENSIONS ARE IN MILLIMETERS.
9. MAXIMUM ALLOWABLE DIE THICKNESS TO BE ASSEMBLED IN THIS PACKAGE FAMILY IS 0.635 MILLIMETERS.
10. THESE DIMENSIONS APPLY TO THE FLAT SECTION OF THE LEAD BETWEEN 0.10 MM AND 0.25 MM FROM THE LEAD TIP.



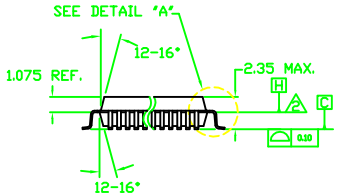
TOP VIEW

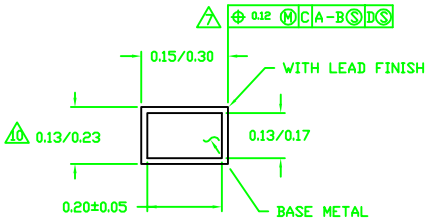


BOTTOM VIEW



DETAIL 'A'





SECTION B-B

DECIMAL	ANGULAR
XX±	±
XXX±	
XXXX±	

MATERIAL

FINISH

DO NOT SCALE DRAWING

PROJECTION

APPROVALS		DATE
DRAWN	JCABR	02/25 1997
CHECKED	TKHAM/CHOIKS	02/25 1997
ENG'R	LCANO	02/25 1997
RELEASED	MHELA	11/19 1997

Anam Industrial Co., LTD. Seoul, Korea
Amkor Electronics Irving, TX
Amkor/Anam Philipines, INC. Manila, Philippines
Amkor Electronics Chandler, AZ

anam amkor EXCELLENCE IN SEMICONDUCTOR ASSEMBLY AND TEST

TITLE: PACKAGE OUTLINE, 64 LEAD, MQFP, 10 X 10 MM BODY, 1.95/0.15 MM FORM, 2.00 MM THICK

SIZE	DWG. NO.	REV.
B	39804	00

SCALE | SHEET 1 OF 1